Features

- ARM7TDMI® ARM® Thumb® Processor Core
 - In-Circuit Emulator, 40 MHz operation
- 16-bit Fixed-point OakDSPCore[®]
 - Up to 60 MHz operations
 - 104K bytes of Integrated Fast RAM, Codec Interface
- Ethernet Bridge
 - Dual Ethernet 10/100 Mbps MAC Interface
 - 16-Kbyte Frame Buffer
- 1 K-Byte Boot ROM, Embedding a Boot Program
 - Enable Application Download from DataFlash®
- External Bus Interface
 - On-chip 32-bit SDRAM Controller
 - 4 Chip Select Static Memory Controller
- Multi-level Priority, Individually Maskable, Vectored Interrupt Controller
- Three 16-bit Timer/Counters
- Two UARTs with Modem Control Lines
- Serial Peripheral Interface (SPI)
- Two PIO Controllers, Managing up to 48 General-purpose I/O Pins
- Supported by a Wide Range of Ready-to-use Application Software
 - Multi-tasking Operating System, Networking
 - Voice-processing Functions
- Available in a 208-lead PQFP Package and 256-ball BGA Package
- Power Supplies
 - VDDIO 3.3V nominal
 - VDDCORE and VDDOSC 1.8V nominal
- 0°C to + 70°C Operating Temperature Range

Description

The AT75C221, Atmel's latest device in the family of smart internet appliance processors (SIAP™), is a high-performance processor designed for professional internet appliance applications such as the Ethernet IP phone. The AT75C221 is built around an ARM7TDMI microcontroller core running at 40 MHz with an OakDSPCore coprocessor running at 60 MHz and a dual Ethernet 10/100 Mbits/sec MAC interface.

In a typical standalone IP phone, the DSP handles the voice processing functions (voice compression, acoustic echo cancellation, etc.) while the dual-port Ethernet 10/100 Mbits/sec MAC interface establishes the connection to the Ethernet physical layer (PHY) that links the network and the PC. In such an application, the power of the ARM7TDMI allows it to run a VoIP protocol stack as well as all the system control tasks.

Atmel provides the AT75C221 with several software modules, including:

- A set of drivers for a Linux[®] kernel capable of driving the embedded peripherals.
- A comprehensive set of tunable DSP algorithms for voice processing, tailored to be run by the DSP subsystem.



Smart Internet Appliance Processor (SIAP[™])

AT75C221

Summary





Pinout

The AT75C221 ships in two alternative packages:

- 208-lead PQFP
- 256-ball BGA

The product features of the 256-ball BGA package are increased compared to the 208-lead PQFP package.

The features available only with the BGA package are:

- The 32-bit wide data bus (In PQFP, only a 16-bit wide data bus is supported.)
- The Parallel I/O lines PA13 to PA18 and PA20 to PA31
- The Parallel I/O lines PB10 to PB16

208-lead PQFP Package Pinout

Table 1. Pinout for 208-lead PQFP Package

Table 1. F	illout for 200-lead
Pin	
Number	Signal Name
1	GND
2	SCLKA
3	VDDIO
4	FSA
5	STXA
6	SRXA
7	NTRST
8	MA_COL
9	MA_CRS
10	MA_TXER
11	MA_TXD0
12	MA_TXD1
13	MA_TXD2
14	MA_TXD3
15	MA_TXEN
16	VDDIO
17	MA_TXCLK
18	GND
19	MA_RXD0
20	MA_RXD1
21	MA_RXD2
22	MA_RXD3
23	MA_RXER
24	MA_RXCLK
25	GND
26	VDDCORE
27	MA_RXDV
28	MA_MDC
29	MA_MDIO
30	MA_LINK
31	MB_COL
32	MB_CRS
33	GND
34	VDDCORE
35	VDDIO
36	MB_TXER

-P Fackage		
Pin		
Number	Signal Name	
37	MB_TXD0	
38	MB_TXD1	
39	MB_TXD2	
40	GND	
41	MB_TXD3	
42	MB_TXEN	
43	MB_TXCLK	
44	MB_RXD0	
45	MB_RXD1	
46	MB_RXD2	
47	MB_RXD3	
48	MB_RXER	
49	MB_RXCLK	
50	MB_RXDV	
51	MB_MDC	
52	VDDIO	
53	GND	
54	MB_MDIO	
55	MB_LINK	
56	A0	
57	A1	
58	A2	
59	A3	
60	A4	
61	A5	
62	A6	
63	A7	
64	A8	
65	A9	
66	A10	
67	A11	
68	A12	
69	VDDIO	
70	GND	
71	A13	
72	A14	

Pin	
Number	Signal Name
73	A15
74	A16
75	A17
76	A18
77	A19B/A0
78	A20/BA1
79	A21
80	D0
81	D1
82	D2
83	D3
84	GND
85	D4
86	VDDIO
87	D5
88	D6
89	D7
90	D8
91	D9
92	D10
93	D11
94	D12
95	D13
96	D14
97	VDDCORE
98	GND
99	D15
100	VDDIO
101	GND
102	VDDIO
103	NC ⁽¹⁾
104	VDDIO
105	GND
106	SDCK
107	SDCS
108	SDA10

Pin	
Number	Signal Name
109	RAS
110	CAS
111	NC ⁽¹⁾
112	WE
113	DQM0
114	DQM1
115	NC ⁽¹⁾
116	GND
117	NC ⁽¹⁾
118	VDDCORE
119	GND
120	VDDOSC
121	PLLRC
122	GND
123	GND
124	XTALOUT
125	XTALIN
126	VDDCORE
127	NCE0
128	NCE1
129	NCE2
130	VDDIO
131	NCE3
132	NWE0
133	NWE1
134	NC ⁽¹⁾
135	VDDIO
136	GND
137	NC ⁽¹⁾
138	NWR
139	NSOE
140	GND
141	VDDCORE
142	VDDIO
143	MISO
144	MOSI





Table 1. Pinout for 208-lead PQFP Package (Continued)

10010 11 1	1110 dt 101 200 10dd 1
Pin	
Number	Signal Name
145	SPCK
146	PA22
147	VDDIO
148	GND
149	NRST
150	FIQ
151	IRQ0
152	TST
153	GND
154	VDDCORE
155	NC ⁽¹⁾
156	VDDIO
157	GND
158	VDDIO
159	TDO
160	TDI

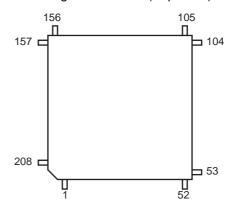
Pin	
Number	Signal Name
161	TMS
162	TCK
163	PA19
164	VDDCORE
165	GND
166	PA12
167	GND
168	VDDIO
169	PA11
170	PA10
171	PA9
172	PA8
173	PA7
174	PA6
175	VDDIO
176	NC ⁽¹⁾

Pin	
Number	Signal Name
177	PA5
178	PA4
179	PA3
180	PA2
181	PA1
182	PA0
183	GND
184	RXDA
185	TXDA
186	NRSTA
187	NCTSA
188	NDTRA
189	NDSRA
190	NDCDA
191	RXDB
192	TXDB

Pin	
Number	Signal Name
193	GND
194	PB0
195	PB1
196	PB2
197	PB3
198	PB4
199	PB5
200	PB6
201	PB7
202	PB8
203	PB9
204	VDDIO
205	DBW32
206	GND
207	BO256
208	VDDIO

Note: 1. NC pins should be left unconnected.

Figure 1. 208-lead PQFP Package Orientation (Top View)



256-ball BGA Package Pinout

Table 1. Pinout for 256-ball BGA Package

Pin	Signal Name
A1	GND
A2	PB9
А3	PB4
A4	PB1
A5	NDSRB
A6	NRSTB
A7	RXDB
A8	NDSRA
A9	TXDA
A10	PA2
A11	PA3
A12	PA6
A13	PA10
A14	PA13
A15	PA15
A16	PA19
A17	NC ⁽¹⁾
A18	PA23
A19	TDO
A20	NC ⁽¹⁾
B1	BO256
B2	PB8
В3	PB7
B4	PB3
B5	PB0
B6	NDTRB
B7	TXDB
B8	NDCDA
B9	NRSTA
B10	PA1
B11	PA5
B12	PA7
B13	PA11
B14	VDDCORE
B15	PA16
B16	PA20
B17	TMS

Pin	Signal Name
B18	TDI
B19	NC ⁽¹⁾
B20	NC ⁽¹⁾
C1	PB10
C2	PA28
С3	DBW32
C4	PB6
C5	PB2
C6	NRIB
C7	NCTSB
C8	NRIA
C9	NCTSA
C10	PA0
C11	PA4
C12	PA8
C13	PA12
C14	PA14
C15	PA18
C16	PA21
C17	TCK
C18	NC ⁽¹⁾
C19	NC ⁽¹⁾
C20	PA31
D1	PB11
D2	PA27
D3	PA26
D4	GND
D5	PB5
D6	VDDIO
D7	NDCDB
D8	GND
D9	NDTRA
D10	RXDA
D11	VDDIO
D12	PA9
D13	GND
D14	PA17

Pin	Signal Name
D15	VDDIO
D16	PA24
D17	GND
D18	PA29
D19	VDDCORE
D20	IRQ1
E1	STXA
E2	FSA
E3	SCLKA
E4	PA25
E17	PA30
E18	TST
E19	IRQ0
E20	NC ⁽¹⁾
F1	PB13
F2	PB12
F3	SRXA
F4	VDDIO
F17	VDDIO
F18	FIQ
F19	NC ⁽¹⁾
F20	SPCK
G1	MA_COL
G2	PB15
G3	PB14
G4	NTRST
G17	NRST
G18	PA22
G19	MOSI
G20	MISO
H1	MA_TXD0
H2	MA_TXER
Н3	MA_CRS
H4	GND
H17	GND
H18	VDDIO
H19	VDDCORE

Pin	Signal Name
H20	NSOE
J1	MA_TXEN
J2	MA_TXD3
J3	MA_TXD2
J4	MA_TXD1
J17	NWR
J18	NWE3
J19	NC ⁽¹⁾
J20	NWE2
K1	MA_RXD0
K2	MA_TXCLK
K3	NC ⁽¹⁾
K4	VDDIO
K17	NWE1
K18	NWE0
K19	NCE3
K20	NCE2
L1	MA_RXD1
L2	MA_RXD2
L3	MA_RXD3
L4	MA_RXER
L17	VDDIO
L18	NCE0
L19	NC ⁽¹⁾
L20	NCE1
M1	MA_RXCLK
M2	VDDCORE
M3	MA_RXDV
M4	MA_MDC
M17	PLLRC
M18	NC ⁽¹⁾
M19	XTALOUT
M20	XTALIN
N1	MA_MDIO
N2	MA_LINK
N3	MB_COL
N4	GND





Table 1. Pinout for 256-ball BGA Package (Continued)

Table I.I	illout for 250-ball be				
Pin	Signal Name				
N17	GND				
N18	DQM3				
N19	VDDCORE				
N20	VDDOSC				
P1	MB_CRS				
P2	VDDCORE				
P3	MB_TXD0				
P4	MB_TXD3				
P17	RAS				
P18	DQM0				
P19	DQM1				
P20	DQM2				
R1	MB_TXER				
R2	MB_TXD1				
R3	MB_TXEN				
R4	VDDIO				
R17	VDDIO				
R18	SDA10				
R19	CAS				
R20	WE				
T1	MB_TXD2				
T2	MB_TXCLK				
Т3	MB_RXD1				
T4	MB_RXER				
T17	D28				
T18	D31				
T19	SDCK				

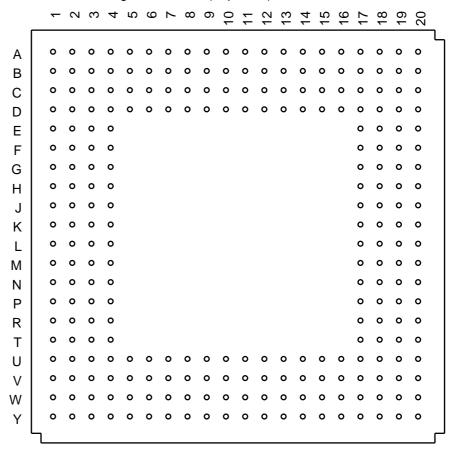
Pin	Signal Name
T20	SDCS
U1	MB_RXD0
U2	MB_RXD2
U3	MB_RXCLK
U4	GND
U5	A1
U6	VDDIO
U7	A8
U8	GND
U9	A17
U10	VDDIO
U11	D3
U12	D7
U13	GND
U14	D16
U15	VDDIO
U16	D22
U17	GND
U18	D27
U19	NC ⁽¹⁾
U20	D30
V1	MB_RXD3
V2	MB_RXDV
V3	NC ⁽¹⁾
V4	A0
V5	A4
V6	A7

Pin	Signal Name
V7	A11
V8	A14
V9	A18
V10	A22
V11	D2
V12	D6
V13	D10
V14	D14
V15	NC ⁽¹⁾
V16	D19
V17	D23
V18	D26
V19	NC ⁽¹⁾
V20	D29
W1	MB_MDC
W2	NC ⁽¹⁾
W3	NC ⁽¹⁾
W4	MB_LINK
W5	A5
W6	A9
W7	A12
W8	A15
W9	A19/BA0
W10	A21
W11	D1
W12	D5
W13	D9

Pin	Signal Name
W14	D12
W15	VDDCORE
W16	D17
W17	D20
W18	D24
W19	VDDIO
W20	NC ⁽¹⁾
Y1	NC ⁽¹⁾
Y2	MB_MDIO
Y3	A2
Y4	A3
Y5	A6
Y6	A10
Y7	A13
Y8	A16
Y9	A20/BA1
Y10	A23
Y11	D0
Y12	D4
Y13	D8
Y14	D11
Y15	D13
Y16	D15
Y17	D18
Y18	D21
Y19	D25
Y20	NC ⁽¹⁾

Note: 1. NC Balls should be left unconnected.

Figure 2. 256-ball Package Orientation (Top View)







Signal Description

Table 1. Signal Description

Block	Signal Name	Function	Туре
	VDDIO	I/O Lines Power Supply	
Memory Controller Static Memory Controller PIO Controller A	VDDCORE	Device Core Power Supply	
Power Supplies	VDDOSC	PLL and Oscillator Power Supply	
	GND	Ground	
Fotomal Declaration	A0-A23	Address Bus	Output
External Bus Interface	D0-D31	Data Bus	Input/Output
	SDCK	SDRAM Clock	Output
	DQM0-DQM3	SDRAM Byte Masks	Output
Synchronous Dynamic Memory Controller	SDCS	SDRAM Chip Select	Output
	SDA10	SDRAM Address Line 10	Output
	RAS	Row Address Strobes	Output
	CAS	Column Address Strobes	Output
	WE	Write Enable	Output
	BA0-BA1	Bank Address Line	Output
	NCE0-NCE3	Chip Selects	Output
Static Memory Controller	NWE0-NWE3	Byte Select/Write Enable	Output
Static Memory Controller	NSOE	Output Enable	Output
	NWR	Memory Block Write Enable	Output
PIO Controller A	PA0-PA31	PIO Controller A I/O Lines	Input/Output
PIO Controller B	PB0-PB15	PIO Controller B I/O Lines	Input/Output
	TCLK0-TCLK2	Timer Counter Clock 0 to 2	Input
Timer Counter	TIOA0-TIOA2	Timer Counter I/O Line A 0 to 2	Input/Output
	TIOB0-TIOA2	Timer Counter I/O Line B 0 to 2	Input/Output
	MISO	Master In/Slave Out	Input/Output
	MOSI	Master Out/Slave In	Input/Output
Serial Peripheral Interface	SPCK	Serial Clock	Input/Output
	NPCS0/NSS	Peripheral Chip Select 0/Slave Select	Input/Output
	NPCS1-NPCS3	Peripheral Chip Select 1 to 3	Output

Table 1. Signal Description (Continued)

Block	Signal Name	Function	Туре
	RXDA-RXDB	Receive Data	Input
UART A and UART B MAC A Interface	TXDA-TXDB	Transmit Data	Output
	NRTSA-NRSTB	Ready to Send	Output
	NCTSA-NCTSB	Clear to Send	Input
UARIA and UARIB	NDTRA-NDTRB	Data Terminal Ready	Output
	NDSRA-NDSRB	Data Set Ready	Input
	NDCDA-NDCDB	Data Carrier Detect	Input
ΛΑC A Interface	NRIA-NRIB	Ring Indicator	Input
	MA_COL	MAC A Collision Detect	Input
	MA_CRS	MAC A Carrier Sense	Input
	MA_TXER	MAC A Transmit Error	Output
	MA_TXD0-MA_TXD3	MAC A Transmit Data Bus	Output
MAC A Interface	MA_TXEN	MAC A Transmit Enable	Output
	MA_TXCLK	MAC A Transmit Clock	Input
	MA_RXD0-MA_RXD3	MAC A Receive Data Bus	Input
	MA_RXER	MAC A Receive Error	Input
	MA_RXCLK	MAC A Receive Clock	Input
	MA_RXDV	MAC A Receive Data Valid	Output
	MA_MDC	MAC A Management Data Clock	Output
	MA_MDIO	MAC A Management Data Bus	Input/Output
	MA_LINK	MAC A Link Interrupt	Input
	MB_COL	MAC B Collision Detect	Input
	MB_CRS	MAC B Carrier Sense	Input
	MB_TXER	MAC B Transmit Error	Output
	MB_TXD0-MB_TXD3	MAC B Transmit Data Bus	Output
	MB_TXEN	MAC B Transmit Enable	Output
	MB_TXCLK	MAC B Transmit Clock	Input
MAC B Interface	MB_RXD0-MB_RXD3	MAC B Receive Data Bus	Input
MAC B Interface	MB_RXER	MAC B Receive Error	Input
	MB_RXCLK	MAC B Receive Clock	Input
	MB_RXDV	MAC B Receive Data Valid	Output
	MB_MDC	MAC B Management Data Clock	Output
	MB_MDIO	MAC B Management Data Bus	Input/Output
	MB_LINK	MAC B Link Interrupt	Input



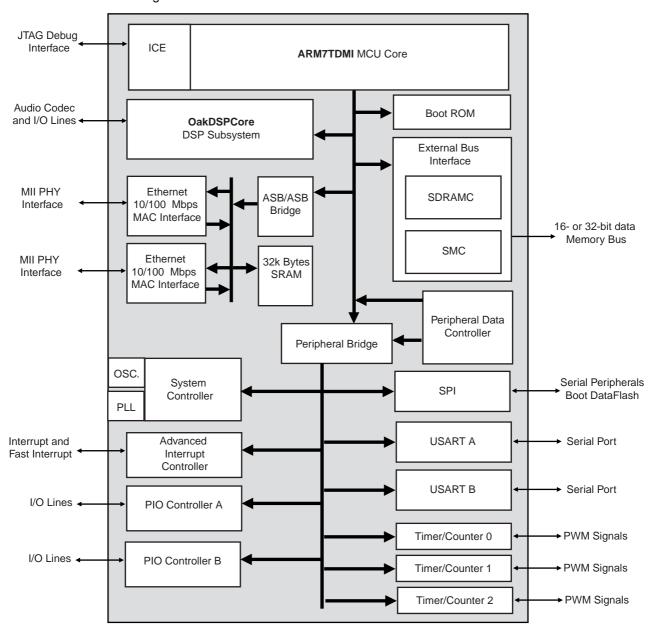


Table 1. Signal Description (Continued)

Block	Signal Name	Function	Туре
	NTRST	Test Reset	Input
	TCK	Test Clock	Input
In-Circuit Emulator	TMS	Test Mode Select	Input
	TDI	Test Data Input	Input
	TDO	Test Data Output	Output
	SCLKA	Serial Clock	Input/Output
Cadaa lutaufaa	FSA	Frame Pulse	Input/Output
Codec Interface	STXA	Transmit Data to Codec	Output
	SRXA	Receive Data to Codec	Input
DCD Cuba ratara	OAKAIN0-OAKAIN1	OakDSPCore User Input	Input
DSP Subsystem	OAKAOUT0-OAKAOUT1	OakDSPCore User Output	Output
	NRST	Reset	Input
	FIQ	Fast Interrupt	Input
	IRQ0-IRQ1	Interrupt Lines	Input
	PLLRC	PLL RC Filter	Analog
Missellansens	XTALIN	Crystal Input	Analog
Miscellaneous	XTALOUT	External Crystal	Analog
	TST	Test Mode	Input
	B0256	Package Size Option (1 = 256 pins)	Input
	DBW32	External Data Bus Width for CS0 (1 = 32 bits)	Input
	ACLKO	ARM Clock Output	Output

Block Diagram

Figure 3. AT75C221 Block Diagram





Application Example

Figure 4. DSP Subsystem

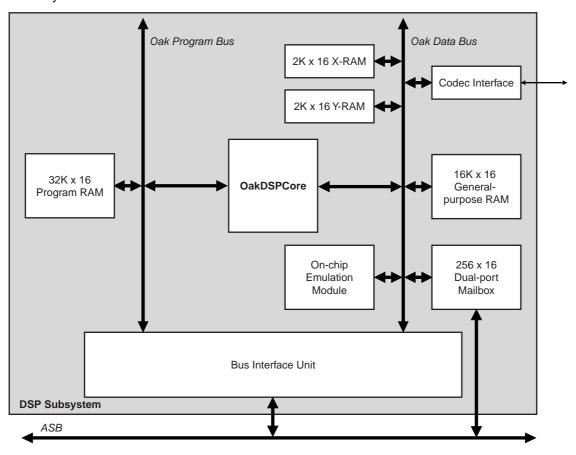
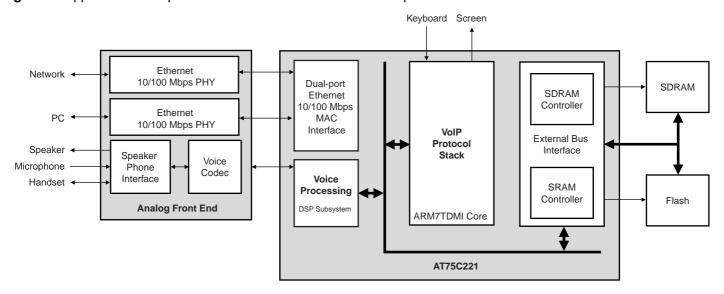


Figure 5. Application Example Overview: Standalone Ethernet Telephone



Functional Description

ARM7TDMI Core

The ARM7TDMI is a three-stage pipeline, 32-bit RISC processor. The processor architecture is Von Neumann load/store architecture, characterized by a single data and address bus for instructions and data. The CPU has two instruction sets: the ARM and the Thumb instruction set. The ARM instruction set has 32-bit wide instructions and provides maximum performance. Thumb instructions are 16-bit wide and give maximum code density.

Instructions operate on 8-bit, 16-bit and 32-bit data types.

The CPU has seven operating modes. Each operating mode has dedicated banked registers for fast exception handling. The processor has a total of 37 32-bit registers, including six status registers.

DSP Subsystem

The AT75C221 DSP subsystem is composed of:

- An OakDSPCore running at 60 MIPS
- 2K x 16 of X-RAM
- 2K x 16 of Y-RAM
- 16K x 16 of General Purpose Data RAM
- 32K x 16 of Loadable Program RAM
- One 256 x 16 Dual-port Mailbox
- One Codec Interface

The DSP subsystem is fully autonomous. The local X- and Y-RAM allows it to reach its maximum processing rate, and a local large data RAM enables complex DSP algorithms to be implemented. The large size of the loadable program RAM permits the use of functions as complex as a low bit-rate vocoder.

During boot time, the ARM7TDMI core has the ability to maintain the OakDSPCore in reset state and to upload DSP code. When the OakDSPCore reverts to an active state, this code is executed.

When the OakDSPCore is running the dual-port mailbox is used as the communication channel between the ARM7TDMI and the OakDSPCore.

A programmable codec interface is directly connected to the OakDSPCore. It allows the connection of most industrial voice, multimedia or data codecs.

Ethernet MAC

The AT75C221 features two identical Ethernet MACs with the same attributes as follows:

- Compatible with IEEE Standard 802.3
- 10 and 100 Mbits per Second Data Throughput Capability
- Full- and Half-duplex Operation
- Media Independent Interface to the Physical Layer
- Register Interface to Address, Status and Control Registers
- DMA Interface
- Interrupt Generation to Signal Receive and Transmit Completion
- 28-byte Transmit and 28-byte Receive FIFOs
- Automatic Pad and CRC Generation on Transmitted Frames





- Address Checking Logic to Recognize Four 48-bit Addresses
- Supports Promiscuous Mode Where All Valid Frames are Copied to Memory
- Supports Physical Layer Management through MDIO Interface

The Ethernet MAC is the hardware implementation of the MAC sub-layer OSI reference model between the physical layer (PHY) and the logical link layer (LLC). It controls the data exchange between a host and a PHY layer according to Ethernet IEEE 802.3u data frame format. The Ethernet MAC contains the required logic and transmit and receive FIFOs for DMA management. In addition, it is interfaced through MDIO/MDC pins for PHY layer management. The Ethernet MAC transfers data in media-independent interface (MII).

Peripheral Multiplexing on PIO Lines

The AT75C221 features two PIO Controllers, PIOA and PIOB, multiplexing I/O lines of the peripheral set.

The PIO Controller A manages 32 I/O lines, PA0 to PA31, but only the I/O lines PA0 to PA12 PA19 and PA22 are available in the 208-lead package.

The PIO Controller B manages only 16 I/O lines, PB0 to PB15, but only the I/O lines PB0 to PB9 are available in the 208-lead package.

Each I/O line of a PIO Controller can be multiplexed with a peripheral I/O.

Power Supplies

The AT75C221 has three types of power supply pins:

- VDDCORE pins power the core, including the ARM7TDMI processor, the DSP subsystem, the memories and the peripherals; voltage is between 1.65V and 1.95V, 1.8V nominal.
- VDDIO pins power the I/O lines, including those of the External Bus Interface and those of the peripherals; voltage is between 3.0V and 3.6V, 3.3V nominal.
- VDDOSC pins power the PLL and oscillator cells; voltage is between 1.65V and 1.95V, 1.8V nominal.

Ground pins are common to all power supplies.

System Controller

The AT75C221 features a System Controller, which takes care of and controls:

- The Test Mode
- The Reset
- The Clocks of the System
- The Chip Identifier

The System Controller manages the reset of the entire system and integrates a clock generator made up of an oscillator and a PLL.

Memory Controller

The AT75C221 architecture is made up of two Advanced System Buses, the ARM ASB and the MAC ASB. Both handle a single memory space.

The ARM ASB handles the access requests of the ARM7TDMI and the PDC. It handles also the access requests coming from the MAC ASB. It connects with the External Bus Interface, the Peripheral Bridge and the Internal Memories, including the mailbox with the DSP Subsystem. It also connects with the MAC ASB.

The MAC ASB handles the access requests of the DMAs of both Ethernet MACs. It also handles the access requests coming from the the ARM ASB. It connects essentially with the Frame Buffer, but also connects with the ARM ASB.

The major advantage of this double-ASB architecture is that the Ethernet traffic does not occupy the main ASB bandwidth, ensuring that the ARM7TDMI can perform at its maximum speed while the Ethernet traffic goes through the Frame Buffer.

Boot Program

The AT75C221 can boot in several ways; including from internal boot software and a hardware connection of DataFlash. When the ARM7TDMI processor is released from reset, it basically attempts a fetch from address 0x00000000. Depending on the hardware configuration, the memory mapping can be altered and thus modify how the system boots.

Peripherals

The Peripheral Bridge allows access to the embedded peripheral user interfaces. It is optimized for low power consumption, as it is built without usage of any clock. However, any access on the peripheral is performed in two cycles.

The AT75C221 peripherals are designed to be programmed with a minimum number of instructions. Each peripheral has 16K bytes of address space allocated in the upper part of the address space.

PDC: Peripheral Data Controller

The AT75C221 features a six-channel Peripheral Data Controller (PDC) dedicated to the two on-chip UARTs and the SPI. One PDC channel is connected to the receiving channel and one to the transmitting channel of each UART and of the SPI.

Each PDC channel operates as DMA (Direct Memory Access).

The User Interface of a PDC channel is integrated in the memory space of each peripheral. It contains a 32-bit address pointer register and a 16-bit count register. When the programmed number of bytes is transferred, an end-of-transfer signal is sent to the peripheral and is visible in the peripheral status register. This status bit might trigger an interrupt.

EBI: External Bus Interface

The External Bus Interface generates the signals which control access to external memories or peripheral devices. It contains two controllers: the SDRAM Controller and the Static Memory Controller and manages the sharing of data and address buses between both controllers.

SDRAMC: SDRAM Controller

The SDRAM Controller extends the memory capabilities of a chip by providing the interface to an external 16- or 32-bit SDRAM device. The page size supports ranges from 2048 to 8192 and the number of columns from 256 to 2048. It supports byte (8-bit), halfword (16-bit) and word (32-bit) accesses. The maximum addressable SDRAM size is 256M bytes.

The SDRAM Controller supports a read or write burst length of one location. It keeps track of the active row in each bank, thus maximizing SDRAM performance, e.g., the application may be placed in one bank and data in the other banks. So as to optimize performance, it is advisable to avoid accessing different rows in the same bank.

The SDRAM Controller's function is to make the SDRAM device access protocol transparent to the user.

SMC: Static Memory Controller

The AT75C221 features a Static Memory Controller that enables interfacing with a wide range of external static memory on peripheral devices, including Flash, ROM, static RAM, and parallel peripherals.

The SMC provides a glueless memory interface to external memory using common address, data bus and dedicated control signals. The SMC is highly programmable and





has up to 24 bits of address bus, a 32- or 16-bit data bus and up to four chip select lines. The SMC supports different access protocols allowing single clock-cycle accesses. The SMC is programmed as an internal peripheral that has a standard APB bus interface and a set of memory-mapped registers. It shares the external address and data buses with the SDMC.

AIC: Advanced Interrupt Controller

The AT75C221 integrates an Advanced Interrupt Controller (AIC) which is connected to the fast interrupt request (nFIQ) and the standard interrupt request (nIRQ) inputs of the ARM7TDMI processor. The processor's nFIQ line can only be asserted by the external fast interrupt request input (FIQ). The nIRQ line can be asserted by the interrupts generated by the on-chip peripherals and the two external interrupt request lines, IRQ0 to IRQ1.

An 8-level priority encoder allows the user to define the priority between the different interrupt sources. Internal sources are programmed to be level-sensitive or edge-triggered. External sources can be programmed to be positive- or negative-edge triggered or high- or low-level sensitive.

PIO: Programmable I/O Controller

The AT75C221 integrates 24 programmable I/O pins. Each pin can be programmed as an input or an output. Each pin can also generate an interrupt. The programmable I/O is implemented as two blocks, called PIO A and PIO B, 32 and 16 pins each, respectively.

These pins are used for several functions:

- External I/O for internal peripherals
- Keypad controller function
- General-purpose I/O

UART: Universal Asynchronous Receiver Transmitter

The AT75C221 provides two identical full-duplex, Universal Asynchronous Receiver Transmitters as UART A and UART B. These peripherals sit on the APB bus but are also connected to the ASB bus (and hence external memory) via a dedicated DMA.

The main features of the UART are:

- Programmable Baud Rate Generator
- Parity, Framing and Overrun Error Detection
- Line Break Generation and Detection
- Automatic Echo, Local Loopback and Remote Loopback Channel Modes
- Interrupt Generation
- Two Dedicated Peripheral Data Controller Channels
- 6-, 7- and 8-bit Character Length
- Modem Control Signals

TC: Timer/Counter

The AT75C221 features a timer/counter block which includes three identical 16-bit timer/counter channels. Each channel can be independently programmed to perform a wide range of functions including frequency measurement, event counting, interval measurement, pulse generation, delay timing and pulse-width modulation.

Each timer/counter channel has three external clock inputs, five internal clock inputs, and two multi-purpose input/output signals that can be configured by the user. Each channel drives an internal interrupt signal that can be programmed to generate processor interrupts via the AIC.

The timer/counter block has two global registers which act upon all three TC channels. The Block Control Register allows the three channels to be started simultaneously with

the same instruction. The Block Mode Register defines the external clock inputs for each timer/counter channel, allowing them to be chained.

SPI: Serial Peripheral Interface

The Serial Peripheral Interface circuit is a synchronous serial data link that provides communication with external devices in Master or Slave Mode. It also allows communication between processors if an external processor is connected to the system.

The Serial Peripheral Interface is essentially a shift register that serially transmits data bits to other SPI's. During a data transfer, one SPI system acts as the "master" which controls the data flow, while the other system acts as the "slave" which has data shifted into and out of it by the master. Different CPU's can take turn being masters (Multiple Master Protocol opposite to Single Master Protocol where one CPU is always the master while all of the others are always slaves), and one master may simultaneously shift data into multiple slaves. However, only one slave may drive its output to write data back to the master at any given time.

The main features of the SPI are:

- Four Chip Selects with External Decoder Support Allow Communication with Up to 15 Peripherals
- Serial Memories, such as DataFlash and 3-wire EEPROMs
- Serial Peripherals, such as ADCs, DACs, LCD Controllers, CAN Controllers and Sensors
- External Coprocessors
- Master or Serial Peripheral Bus Interface
- 8- to 16-bit Programmable Data Length Per Chip Select
- Programmable Phase and Polarity Per Chip Select
- Programmable Transfer Delays Between Consecutive Transfers and Between Clock and Data Per Chip Select
- Programmable Delay Between Consecutive Transfers
- Selectable Mode Fault Detection
- Connection to PDC Channel Capabilities Optimizes Data Transfers
- One Channel for the Receiver, One Channel for the Transmitter





Ordering Information

Table 2 below provides package ordering information for the AT75C221.

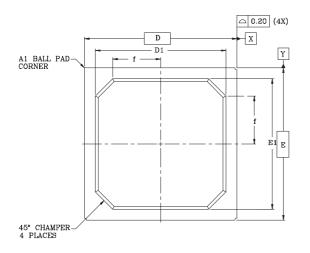
Table 2. Ordering Information

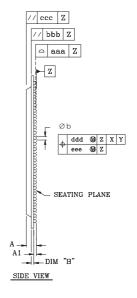
Ordering Code	Package	Operating Temperature Range
AT75C221-Q208	PQFP208	0° to 70° C
AT75C221-C256	BGA256	0° to 70° C

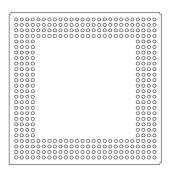
Mechanical Characteristics and Packaging Information

BGA Packaging Information

Figure 6. AT75C221 BGA Package







Perimeter array 4 rows

BOTTOM VIEW

For BGA package data, see Table 3 on page 20,



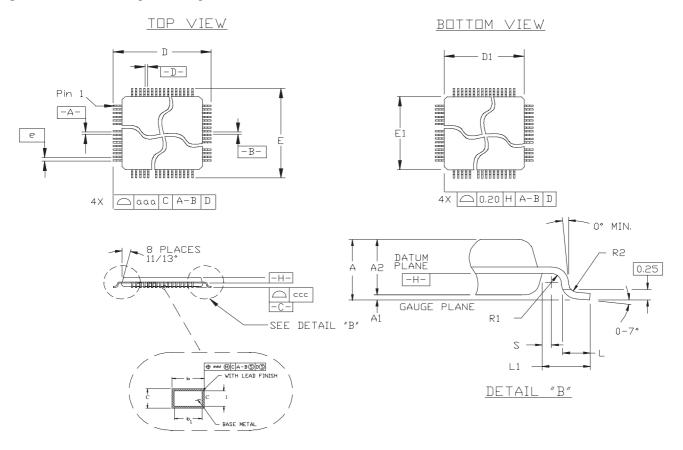
BGA Package Data

Table 3. Dimensions (mm)

Symbol	Min	Nom	Max
A1	0.50	0.60	0.70
Øb	0.60	0.75	0.90
aaa		0.30	
bbb		0.25	
ccc		0.35	
ddd		0.30	
eee		0.15	
Α	1.92	2.13	2.34
В	0.28	0.32	0.38
D/E	26.8	27.0	27.2
D1/E1		24.0	24.7
е		1.27	
f		8.05	

PQFP Packaging Information

Figure 7. PQFP Package Drawing



For package data, see Table 4, Table 5 and Table 6 on page 22.



PQFP Package Data

Table 4. Dimensions (mm)

Symbol	Min	Nom	Max
С	0.11		0.23
c1	0.11	0.15	0.19
L	0.65	0.88	1.03
L1		1.60 REF	
R2	0.13		0.3
R1	0.13		
S	0.4		
	Tolerances of Form a	nd Position	
aaa		0.25	
ccc			0.10

Table 5. Dimensions specific to PQFP Package (mm)

Α	A 1	A2		k)		b1		D	D1	E	E1	е	ddd	
Max	Min	Min	Nom	Max	Min	Max	Min	Nom	Max	BSC	BSC	BSC	BSC	BSC	BSC
4.10	0.25	3.20	3.40	3.60	0.17	0.27	0.17	0.20	0.23	31.20	28.00	31.20	28.00	0.50	0.10

Table 6. 208-lead PQFP Package Electrical Characteristics

Body	R (mΩ)		C _s ((pF)	C _m	(pF)	L _s (nH)	L _m ((nH)
Size	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
28 x 28	53	71	1.4	1.7	0.56	0.73	6.7	8.4	3.9	5.1



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